

32 K × 8 High Speed CMOS SRAM

Short description. Please refer to the full datasheet available on TEMIC web for detailed technical information.

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Description

The HM 65756 is a high speed CMOS static RAM organised as 32,768 × 8 bits. It is manufactured using TEMIC's high performance CMOS technology.

Access time as fast as 15 ns are available with maximum power consumption of only 880 mW.

The HM 65756 features fully static operation requiring no external clocks or timing strobes. The automatic power-down feature reduces the power consumption by 80 % when the circuit is deselected.

Easy memory expansion is provided by an active low chip select (\overline{CS}) an active low output enable (\overline{OE}), and three state drivers.

All inputs or outputs of the HM-65756 are TTL compatible and operate from single 5 V supply thus simplifying system design.

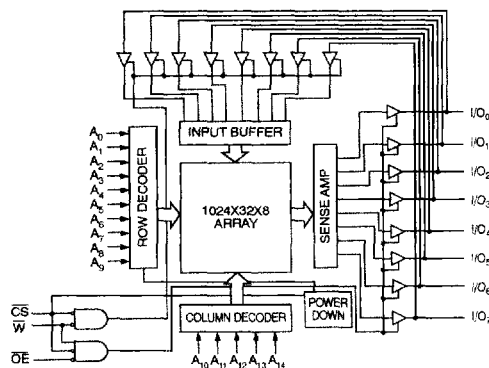
For military application the HM 65756 is processed according to the methods of the latest revision of the MIL STD 883.

Features

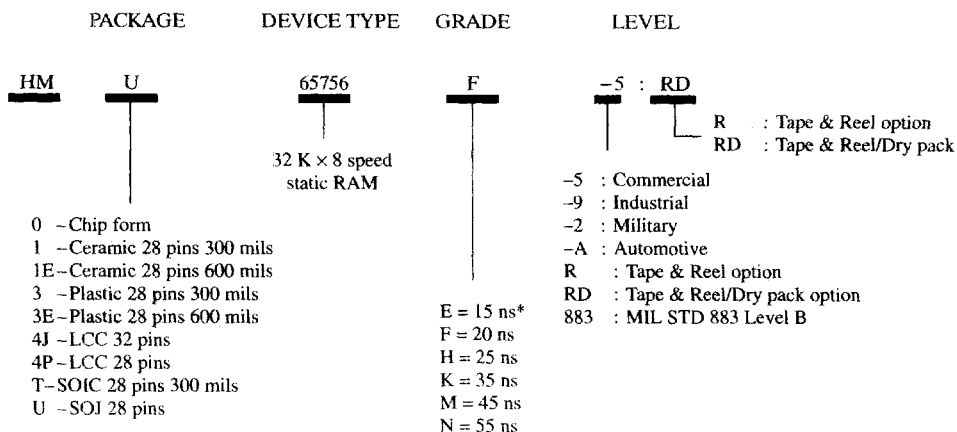
- Fast access time
 - Commercial : 15/20/25/35/45/55ns
 - Industrial : 20/25/35/45/55ns
 - Automotive/military : 25/35/45/55ns
- Low power consumption
 - Active : 880 mW
 - Standby : 220 mW
- Wide temperature range :
 - 55°C to + 125°C
- 300 and 600 mils width package
- TTL compatible inputs and outputs
- Asynchronous
- Capable of withstanding greater than 2 000 V electrostatic discharge
- Output enable
- Single 5 volt supply
- 3.3 v versions are also available (see L65756 spec)

Interface

Block Diagram



Ordering Information



* available in commercial range on PDIL.3 (code 3) and SOJ (code U). For other package please consult your sales office.

Military Version

The following table gives package/access time/process flow available combinations

Temp. range	Packages	Access Time (ns)				Std process 65756 Mil flows (including SMD5962-88662)
		25 (H)	35 (K)	45 (M)	55 (N)	
M	1 1E 4J 4P 0	● ● ● ● X	● ● ● ● X	● ● ● ● X	● ● ● ● ●	● ● ● ● ●

● = product in production

X = call sales office for availability

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